ABSTRACT

Sheet sticking apparatus 10 that cuts sheet material S laminated with die bonding sheet DS on one surface of base sheet BS to a plane shape of a semiconductor wafer to form a sticking area A1 and sticks the area to the wafer. The apparatus includes cutting means 15 that forms the area A1 and peeling area A2, first peeling means 17 that peels the area A2, sticking table 62 that sticks the area A1 to the wafer and second peeling means 20 that peels the base sheet from the area A1. The cutting means 15 includes first through third cutting blades 31A, 31B, and 31C. The first blade 31A forms the area A1. Part of the first blade 31A and the second and third blades 31B, 31C form the area A2. After peeling off the area A2, the area A1 is stuck to the wafer.